

HSF

NOTES:

Rated Current: 5.0AMP.(20°C,1*2P-1*15P)
 3.0AMP.(20°C,1*16P-1*40P) **A2**

Contact Resistance: 20mΩ Max.

Withstand Voltage: 1000V AC/DC

Insulation Resistance: 1000MΩ Min.

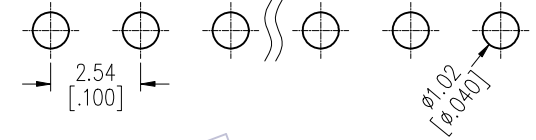
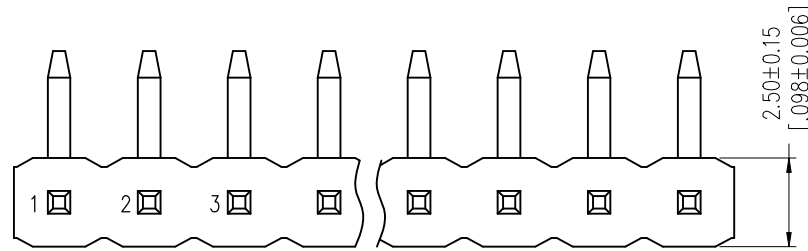
Operation Temperature: -40°C to +125°C(Gold Plating)
 -40°C to +105°C(Tin Plating) **A2**

Contact Material: Copper Alloy

Contact Plating: Au or Sn Over 30u" Min Ni **A2**

Insulator Material: PA9T+G.F UL94V-0 BK **A2**

Recommended P.C.B Layout (Top Side)
 (PCB BOARD TOLERANCE±0.05)
 (PCB Thickness: T=1.60m)



Ordering Information

1120-1 1 XX XX R XXX C 0 XX **A2**

Plastic Layer

Plastic Row

No. of Pins

Per Row: 02-40

Contact Plating

G0=Gold Flash

G3=10u"Au, BG3=8u"PdNi+2u"Au

G4=15u"Au, BG4=13u"PdNi+2u"Au

G5=30u"Au, BG5=28u"PdNi+2u"Au

S0=Gold Flash/Tin

S3=10u"Au/Sn, P3=8u"PdNi+2u"Au/Sn

S4=15u"Au/Sn, P4=13u"PdNi+2u"Au/Sn

S5=30u"Au/Sn, P5=28u"PdNi+2u"Au/Sn **A2**

SN=Bright Tin

SM=Matte Tin

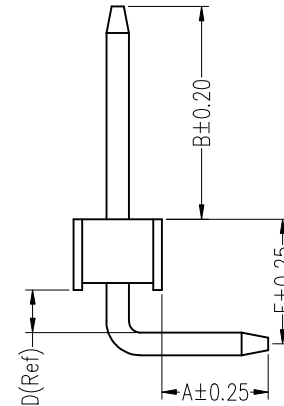
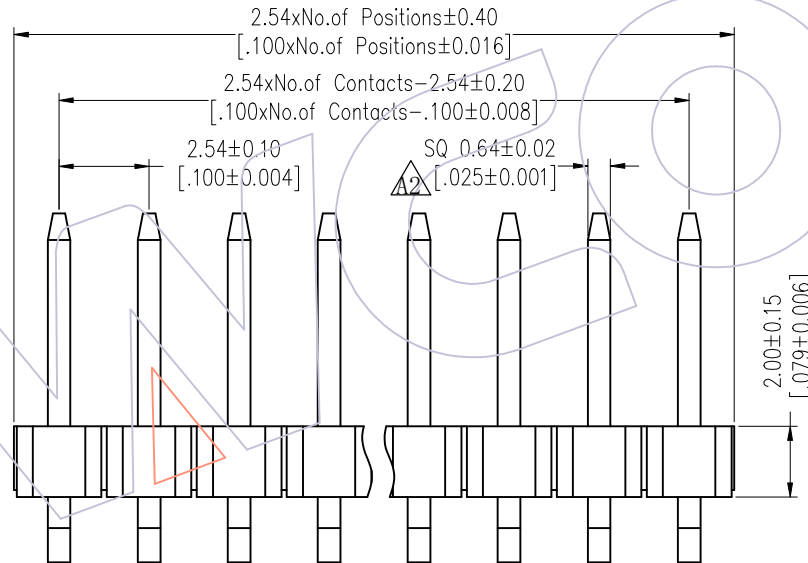
Series No. 01-99

Packing 0=PE Bag

Insulator Material C=PA9T(Standard)

Pin Length L(See Table)

Type: R=R/A



Item	Pin Length	A	D	E	B	Mating
Standard	10.8	3.00	1.2	3.52	3.5	2135/2150T/2157 A2
	11.3				4.0	2145/2150
	12.3				5.0	2168T/2171T
	13.0				5.84	2171/2185X
Standard	9.8	2.0 (THR)	1.2	3.52	3.5	2135/2150T/2157
	10.3				4.0	2145/2150
	11.3				5.0	2168T/2171T
	12.0				5.84	2171/2185X
Alternate						

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	Fit	PART NO.
A2	2025/03/26	Standardization Drawing	CP	x.X ±0.40	CP	2025/03/26	UNIT	mm	1120-11XXXXRXXXCOXX
A1	2018/01/22	Modify P/N	Ruipeng	x.XX ±0.25	CHECK	DATE	SIZE	A4	TITLE:
A0	2012/05/07	NEW	William Chen	x.XXX ±0.15	TANG	2025/03/26	SHEET	1/2	PH2.54 SINGLE ROW 90° H=2.0 CONCAVE BENDING
				Angle ± 3'	APPROVE	DATE	PROJ.		Customer NO.
				DIM TOL	Steven Zhao	2025/03/26			

WCON
 Http: www.wcon.com

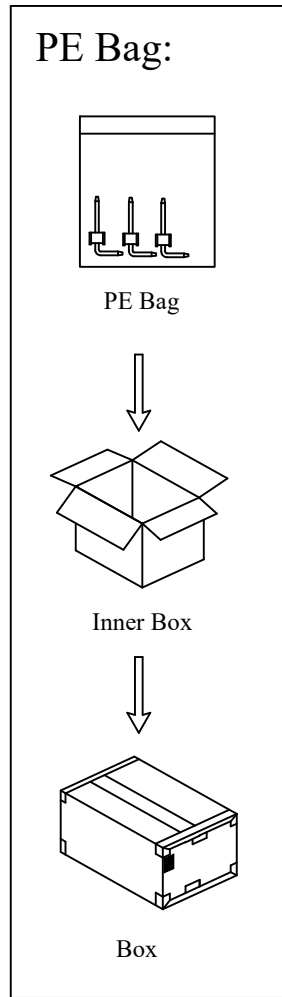
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HSF

Packing:

Packaging Quantity Refers To The Following Table



PINS	Q' ty/Bag (L ≤ 10.0)	PINS	Q' ty/Bag (L ≤ 10.0)	PINS	Q' ty/Bag (10.0 < L ≤ 16.0)	PINS	Q' ty/Bag (10.0 < L ≤ 16.0)
1	1000	21	400	1	1000	21	200
2	1000	22	400	2	1000	22	200
3	1000	23	400	3	1000	23	200
4	1000	24	400	4	1000	24	200
5	1000	25	400	5	1000	25	200
6	1000	26	200	6	1000	26	200
7	1000	27	200	7	1000	27	200
8	1000	28	200	8	1000	28	200
9	500	29	200	9	500	29	200
10	500	30	200	10	500	30	200
11	500	31	200	11	500	31	200
12	500	32	200	12	500	32	200
13	500	33	200	13	500	33	200
14	500	34	200	14	500	34	200
15	500	35	200	15	300	35	200
16	500	36	200	16	300	36	200
17	500	37	200	17	300	37	200
18	400	38	200	18	300	38	200
19	400	39	200	19	300	39	150
20	400	40	200	20	200	40	150

				OPERATION	DRAW	DATE	SCALE	Fit	PART NO.	 Http: www.wcon.com WCON-Dongguan Tel: +86 769 85358920 WCON-Kunshan Tel: +86 512 57468408 Fax: +86 769 85358915 E-mail: sales@wcon.com
A2	2025/03/26	Standardization Drawing	CP	x.X ±0.40	CP	2025/03/26	UNIT	mm	1120-11XXXXRXXC0XX	
A1	2018/01/22	Modify P/N	Ruipeng	x.XX ±0.25	CHECK	DATE	SIZE	A4	TITLE:	
A0	2012/05/07	NEW	William Chen	x.XXX ±0.15	TANG	2025/03/26	SHEET	2/2	PH2.54 SINGLE ROW 90° H=2.0 CONCAVE BENDING	
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	Angle ± 3'	APPROVE	DATE	PROJ.	Customer NO.		
				DIM TOL	Steven Zhao	2025/03/26				